



Shin-Etsu Silicones of America, Inc.
800-544-1745

FE-221U

Product Description

Shin-Etsu FE-221 U is a low durometer fluorosilicone base which readily accepts extending fillers for compounding to higher durometers.

Product Features

- Excellent fuel and solvent resistance.
- Usable over a broad temperature range.

Typical Applications

- Chemical resistant packings and seals.
- Oil and fuel resistant seals, O rings, diaphragms for automotive.
- Heat and cold resistant packings, gaskets for aeronautical.

Packaging Information

44lb Box

Typical Properties

Type of HCR	Fluorosilicone
Cure Agent	DBPH
Durometer	20
Tensile Strength (psi)	1340
Elongation (%)	101
Specific Gravity	1.38
Tear Die B (ppi)	87
Compression Set (%)	18
Comp. Set Time (hours)	22
Comp. Set Temp. (°C)	177
Comp. Set Temp. (°F)	350.6

Note: Values are not for specification purposes.

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